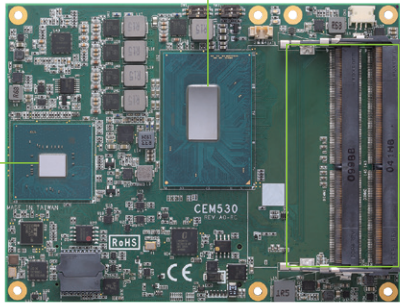


CEM530

COM Express Type 6 Basic Module with Intel® Xeon® or 9th/8th Gen Intel® Core™ Processor and Intel® CM246/QM370

Intel® Xeon® or 9th/8th gen Intel® Core™ processor

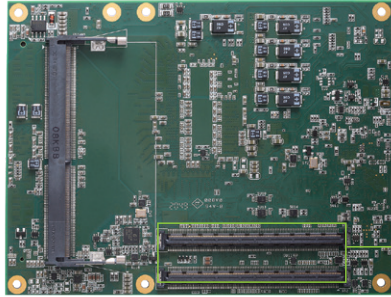
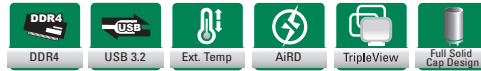
Intel® CM246/
QM370



2 x DDR4
SO-DIMM

Features

- Intel® Xeon® or 9th/8th gen Intel® Core™ processor
- Intel® CM246/QM370 chipset
- Dual channel DDR4-2666 SO-DIMM for up to 64GB of memory
- 1 PCIe x16 and 8 PCIe x1 Gen3
- 4 SATA Gen3 with RAID 0/1/5/10
- 4 USB 3.2 and 8 USB 2.0
- Supports TPM 2.0



COM Express
interface connector

▲ Rear view

Specifications

Core System

CPU	Intel® Xeon® or 9th/8th gen Intel® Core™ processor (Coffee Lake & Coffee Lake Refresh)
System Memory	Dual channel DDR4-2666 SO-DIMM, up to 64GB (or 96GB by request)
Chipset	Intel® CM246/Intel® QM370
BIOS	AMI uEFI (Legacy Free)
Storage	N/A
Watchdog Timer	65536 levels, 0 to 65535 sec.
Expansion Interface	1 x PCIe x16 Gen3 8 x PCIe x1 Gen3
Battery Lithium	N/A
Power Input	ATX: +12V, +5VSB; AT: +12V

Display

Chipset	Intel® Gen 9 HD Graphic Gfx APIs- DX11/12, OCL2.x, OGL 4.3/4.4 3 independent displays
Display Interface	1 x LVDS; 18/24-bit single/dual channel (default), optional with eDP 1.4: 4096 x 2304 @60Hz 1 x VGA; 1920 x 1200 @60Hz (default) 2 x DDI (DisplayPort 1.2: 4096 x 2304 @60Hz/HDMI 1.4: 4096 x 2160 @30/24Hz)

I/O

SATA	4 x SATA Gen3 with RAID 0/1/5/10
Hardware Monitoring	Yes
Ethernet	1 x 10/100/1000 Mbps Ethernet with Intel® I219-LM; supports Wake-on-LAN, PXE Boot ROM
Audio	HD link interface to baseboard for Codec
USB	4 x USB 3.2 Gen2 8 x USB 2.0
Serial	1 x LPC 1 x SPI 2 x TX/RX
TPM	TPM 2.0
SMBus	Yes
Others	1 x I ² C
GPIO	4-CH in & 4-CH out (SDIO optional)
Smart Battery	Yes

Mechanical and Environmental

Dimensions	125 x 95 mm
Board Thickness	2.0 mm
Operating Temperature	-40°C to +85°C (-40°F to +185°F) with system thermal solution (operation with heatsink and fan)
Humidity	10%- 95% relative humidity, non-condensing
Vibration	3.5 Grms

Packing List

Quick installation guide

Ordering Information

Standard

CEM530-E-2276ME+ CM246 (P/N: E38D530106)	COM Express Type 6 basic module with Intel® Xeon® E-2276ME, CM246, DDI/LVDS, GbE LAN, USB 3.0, and TPM
CEM530-i7-9850HE+ QM370 (P/N:E38D530107)	COM Express Type 6 basic module with Intel® Core™ i7-9850HE, QM370, DDI/LVDS, GbE LAN, USB 3.0, and TPM
CEM530-i3-9100HL+ QM370 (P/N:E38D530102)	COM Express Type 6 basic module with Intel® Core™ i3-9100HL, QM370, DDI/LVDS, GbE LAN, USB 3.0, and TPM
CEM530-G4930E+ CM246 (P/N: E38D530105)	COM Express Type 6 basic module with Intel® Core™ G4930E, CM246, DDI/LVDS, GbE LAN, USB 3.0, and TPM
CEM530-E-2176ME+ CM246 (P/N: E38D530108)	COM Express Type 6 basic module with Intel® Xeon® E-2176ME, CM246, DDI/LVDS, GbE LAN, USB 3.0, and TPM
CEM530-i7-8850H+ QM370 (P/N: E38D530110)	COM Express Type 6 basic module with Intel® Core™ i7-8850H, QM370, DDI/LVDS, GbE LAN, USB 3.0, and TPM
CEM530-i5-8400H+ QM370 (P/N: E38D530111)	COM Express Type 6 basic module with Intel® Core™ i5-8400H, QM370, DDI/LVDS, GbE LAN, USB 3.0, and TPM
CEM530-i3-8100H+ QM370 (P/N: E38D530113)	COM Express Type 6 basic module with Intel® Core™ i3-8100H, QM370, DDI/LVDS, GbE LAN, USB 3.0, and TPM

*Any other SKUs (9th or 8th gen Intel® Core™ processor) and combination are supported by request. Please contact sales for the details.

Optional

CEB94011 (P/N: E394011100)	CEB94011 COM Express Type 6 evaluation board
E39J015100	CEM530/CEM520 heat sink with fan
E39J006100	CEM530/CEM520 heat spreader

*CEM530 shared the same thermal solution with CEM520.

Block Diagram

